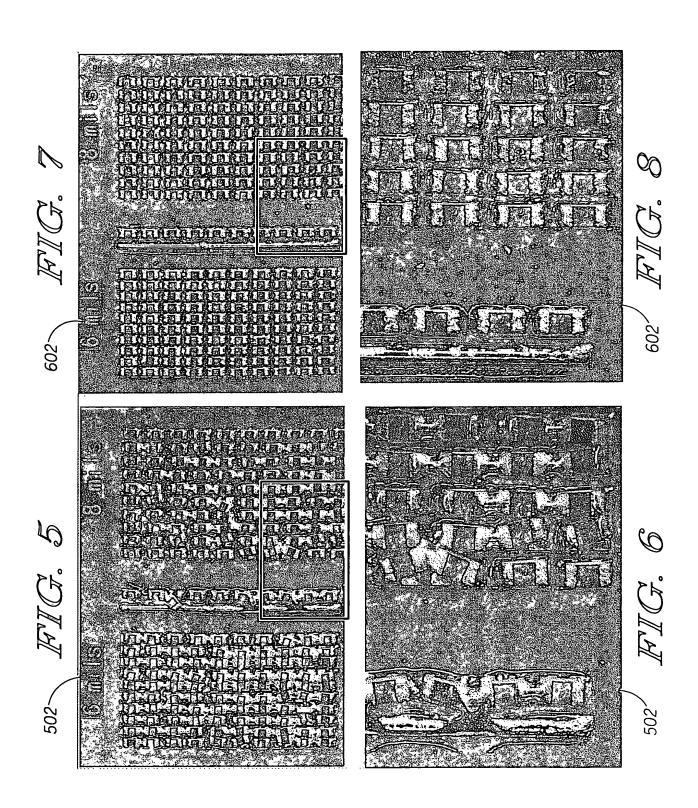


FIG. 4



BEST AVAILABLE COPY

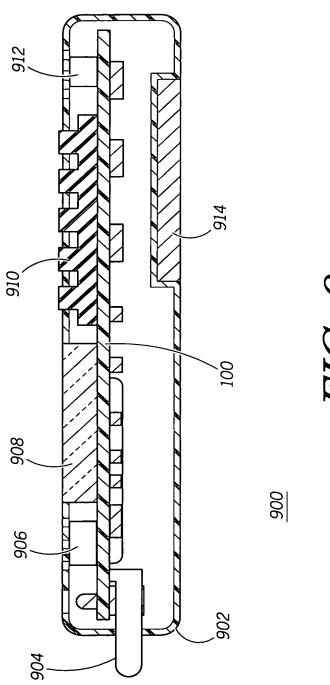


FIG. 9

5/5 **START** 1*Ò*02 FABRICATE PRINTED WIRING BOARD WITH EXPOSED COPPER PADS 1Ò04 COAT COPPER PADS WITH ORGANIC SOLDERABILITY PRESERVATIVE DEPOSIT OVERSIZED PATCHES OF LEAD-FREE SOLDER PASTE ON 1006 ONE OR MORE PADS SUCH THAT PATCHES OF DEPOSITED LEAD-FREE SOLDER ARE WITHIN 0.25 MILLIMETERS OF EACH OTHER PLACE ELECTRICAL COMPONENTS ON PRINTED WIRING BOARD 1008 SUCH THAT CONTACT AREAS OF THE ELECTRICAL COMPONENTS ARE IN CONTACT WITH THE SOLDER PASTE 1Ò10 HEAT PRINTED WIRING BOARD IN AN AIR ATMOSPHERE TO A TEMPERATURE ABOVE A LIQUIDOUS TEMPERATURE OF SOLDER INCLUDED IN THE SOLDER PASTE FIG. 10 **STOP** 1100 1100. 1108 1104 1102 1102 1106 1106 ਖ  $\Box$ 1202 1206 1108 1104 1204 1208 1110 1110 FIG. 11 FIG. 12 1206 1208 / 1100 1402 1202 1408 1110~ 1204 1110~ 1100 1406 1406 FIG. 13 FIG. 14